



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Ifw  
10/770,941

In re Application of:

Chad A. Cobbley et al.

Prior Application Serial No.: 10/672,750

Prior Application Filed:

September 25, 2003

Serial No.: ~~10/771,085~~ 10/770,941

Filed: February 03, 2004

For: STACKED DIE MODULE AND  
TECHNIQUES FOR FORMING A  
STACKED DIE MODULE

Group Art Unit: 2813

Examiner: Blum, David S.

Atty Docket: MICS:0078—2 (FLE)  
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Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

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37 C.F.R. 1.8

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December 8, 2004  
Date

Kerri Hyland

Sir:

**RESPONSE AND AMENDMENT**

In response to the Official Action mailed on September 08, 2004, Applicants respectfully request reconsideration of the above-identified application in view of the amendments and remarks set forth below.